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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	20-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1509-e-p

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3.3.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- · the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

REGISTER 3-1: STATUS: STATUS REGISTER

For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as '000u uluu' (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 28.0 "Instruction Set Summary"**).

Note 1: The <u>C</u> and <u>DC</u> bits operate as Borrow and <u>Digit</u> Borrow out bits, respectively, in subtraction.

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
		_	TO	TO PD		DC ⁽¹⁾	C ⁽¹⁾
bit 7					•		bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimple	mented bit, read	l as '0'	
u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all othe						ther Resets	
'1' = Bit is set '0' = Bit is cleared g = Value depends on condition							

bit 7-5	Unimplemented: Read as '0'
bit 4	TO: Time-Out bit
	 1 = After power-up, CLRWDT instruction or SLEEP instruction 0 = A WDT time-out occurred
bit 3	PD: Power-Down bit
	 1 = After power-up or by the CLRWDT instruction 0 = By execution of the SLEEP instruction
bit 2	Z: Zero bit
	 1 = The result of an arithmetic or logic operation is zero 0 = The result of an arithmetic or logic operation is not zero
bit 1	DC: Digit Carry/Digit Borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions) ⁽¹⁾
	 1 = A carry-out from the 4th low-order bit of the result occurred 0 = No carry-out from the 4th low-order bit of the result
bit 0	C: Carry/Borrow bit ⁽¹⁾ (ADDWF, ADDLW, SUBLW, SUBWF instructions) ⁽¹⁾
	 1 = A carry-out from the Most Significant bit of the result occurred 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For Borrow, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

5.2 Clock Source Types

Clock sources can be classified as external, internal or peripheral.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (ECH, ECM, ECL modes), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (EXTRC) mode circuits.

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators that are used to generate the internal system clock sources: the 16 MHz High-Frequency Internal Oscillator (HFINTOSC) and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The peripheral clock source is a nominal 600 kHz internal RC oscillator, FRC. The FRC is traditionally used with the ADC module, but is sometimes available to other peripherals. See **Section 5.2.2.4** "**Peripheral Clock Sources**".

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 5.3 "Clock Switching**" for additional information.

5.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
 - Secondary oscillator during run-time, or
 - An external clock source determined by the value of the FOSC bits.

See **Section 5.3 "Clock Switching**" for more information.

5.2.1.1 EC Mode

The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 5-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through the Fosc bits in the Configuration Words:

- ECH High-power, 4-20 MHz
- ECM Medium-power, 0.5-4 MHz
- ECL Low-power, 0-0.5 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC[®] MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.





5.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 5-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 5-3 and Figure 5-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

6.12 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON registers are updated to indicate the cause of the Reset. Table 6-3 and Table 6-4 show the Reset conditions of these registers.

STKOVF	STKUNF	RWDT	RMCLR	RI	POR	BOR	то	PD	Condition
0	0	1	1	1	0	x	1	1	Power-on Reset
0	0	1	1	1	0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	1	1	1	0	x	x	0	Illegal, \overline{PD} is set on \overline{POR}
0	0	u	1	1	u	0	1	1	Brown-out Reset
u	u	0	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	u	0	u	u	u	u	u	MCLR Reset during normal operation
u	u	u	0	u	u	u	1	0	MCLR Reset during Sleep
u	u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 6-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

TABLE 6-4: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	1 1000	00 110x
MCLR Reset during normal operation	0000h	u muumuu	uu Ouuu
MCLR Reset during Sleep	0000h	1 Ouuu	uu Ouuu
WDT Reset	0000h	0 muumuu	uu uuuu
WDT Wake-up from Sleep	PC + 1	0 Ouuu	uu uuuu
Brown-out Reset	0000h	1 luuu	00 11u0
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	1 Ouuu	uu uuuu
RESET Instruction Executed	0000h	u uuuu	uu u0uu
Stack Overflow Reset (STVREN = 1)	0000h	u uuuu	lu uuuu
Stack Underflow Reset (STVREN = 1)	0000h	u uuuu	ul uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and the Global Interrupt Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

21.4.9 ACKNOWLEDGE SEQUENCE

The ninth SCLx pulse for any transferred byte in I^2C is dedicated as an Acknowledge. It allows receiving devices to respond back to the transmitter by pulling the SDAx line low. The transmitter must release control of the line during this time to shift in the response. The Acknowledge (ACK) is an active-low signal, pulling the SDAx line low indicated to the transmitter that the device has received the transmitted data and is ready to receive more.

The result of an \overline{ACK} is placed in the ACKSTAT bit of the SSPxCON2 register.

Slave software, when the AHEN and DHEN bits are set, allow the user to set the ACK value sent back to the transmitter. The ACKDT bit of the SSPxCON2 register is set/cleared to determine the response.

Slave hardware will generate an ACK response if the AHEN and DHEN bits of the SSPxCON3 register are clear.

There are certain conditions where an \overline{ACK} will not be sent by the slave. If the BF bit of the SSPxSTAT register or the SSPOV bit of the SSPxCON1 register are set when a byte is received.

When the module is addressed, after the eighth falling edge of SCLx on the bus, the ACKTIM bit of the SSPxCON3 register is set. The ACKTIM bit indicates the acknowledge time of the active bus. The ACKTIM Status bit is only active when the AHEN bit or DHEN bit is enabled.

21.5 I²C Slave Mode Operation

The MSSP Slave mode operates in one of four modes selected in the SSPM bits of SSPxCON1 register. The modes can be divided into 7-bit and 10-bit Addressing mode. 10-bit Addressing modes operate the same as 7-bit with some additional overhead for handling the larger addresses.

Modes with Start and Stop bit interrupts operate the same as the other modes with SSPxIF additionally getting set upon detection of a Start, Restart, or Stop condition.

21.5.1 SLAVE MODE ADDRESSES

The SSPxADD register (Register 21-6) contains the Slave mode address. The first byte received after a Start or Restart condition is compared against the value stored in this register. If the byte matches, the value is loaded into the SSPxBUF register and an interrupt is generated. If the value does not match, the module goes idle and no indication is given to the software that anything happened.

The SSP Mask register (Register 21-5) affects the address matching process. See **Section21.5.9** "**SSPx Mask Register**" for more information.

21.5.1.1 I²C Slave 7-bit Addressing Mode

In 7-bit Addressing mode, the LSb of the received data byte is ignored when determining if there is an address match.

21.5.1.2 I²C Slave 10-bit Addressing Mode

In 10-bit Addressing mode, the first received byte is compared to the binary value of '1 1 1 1 0 A9 A8 0'. A9 and A8 are the two MSbs of the 10-bit address and stored in bits 2 and 1 of the SSPxADD register.

After the acknowledge of the high byte the UA bit is set and SCLx is held low until the user updates SSPxADD with the low address. The low address byte is clocked in and all eight bits are compared to the low address value in SSPxADD. Even if there is not an address match; SSPxIF and UA are set, and SCLx is held low until SSPxADD is updated to receive a high byte again. When SSPxADD is updated the UA bit is cleared. This ensures the module is ready to receive the high address byte on the next communication.

A high and low address match as a write request is required at the start of all 10-bit addressing communication. A transmission can be initiated by issuing a Restart once the slave is addressed, and clocking in the high address with the R/W bit set. The slave hardware will then acknowledge the read request and prepare to clock out data. This is only valid for a slave after it has received a complete high and low address byte match.

21.5.2 SLAVE RECEPTION

When the R/\overline{W} bit of a matching received address byte is clear, the R/\overline{W} bit of the SSPxSTAT register is cleared. The received address is loaded into the SSPxBUF register and acknowledged.

When the overflow condition exists for a received address, then not Acknowledge is given. An overflow condition is defined as either bit BF of the SSPxSTAT register is set, or bit SSPOV of the SSPxCON1 register is set. The BOEN bit of the SSPxCON3 register modifies this operation. For more information see Register 21-4.

An MSSP interrupt is generated for each transferred data byte. Flag bit, SSPxIF, must be cleared by software.

When the SEN bit of the SSPxCON2 register is set, SCLx will be held low (clock stretch) following each received byte. The clock must be released by setting the CKP bit of the SSPxCON1 register, except sometimes in 10-bit mode. See **Section21.2.3 "SPI Master Mode"** for more detail.

21.5.2.1 7-bit Addressing Reception

This section describes a standard sequence of events for the MSSP module configured as an I^2C slave in 7-bit Addressing mode. Figure 21-14 and Figure 21-15 are used as visual references for this description.



21.5.4 SLAVE MODE 10-BIT ADDRESS RECEPTION

This section describes a standard sequence of events for the MSSP module configured as an I^2C slave in 10-bit Addressing mode.

Figure 21-20 is used as a visual reference for this description.

This is a step by step process of what must be done by slave software to accomplish I^2C communication.

- 1. Bus starts idle.
- Master sends Start condition; S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
- 3. Master sends matching high address with R/\overline{W} bit clear; UA bit of the SSPxSTAT register is set.
- 4. Slave sends ACK and SSPxIF is set.
- 5. Software clears the SSPxIF bit.
- 6. Software reads received address from SSPxBUF clearing the BF flag.
- 7. Slave loads low address into SSPxADD, releasing SCLx.
- 8. Master sends matching low address byte to the slave; UA bit is set.

Note: Updates to the SSPxADD register are not allowed until after the ACK sequence.

9. Slave sends ACK and SSPxIF is set.

Note: If the low address does not match, SSPxIF and UA are still set so that the slave software can set SSPxADD back to the high address. BF is not set because there is no match. CKP is unaffected.

- 10. Slave clears SSPxIF.
- 11. Slave reads the received matching address from SSPxBUF clearing BF.
- 12. Slave loads high address into SSPxADD.
- 13. Master clocks a data byte to the slave and clocks out the slaves ACK on the ninth SCLx pulse; SSPxIF is set.
- 14. If SEN bit of SSPxCON2 is set, CKP is cleared by hardware and the clock is stretched.
- 15. Slave clears SSPxIF.
- 16. Slave reads the received byte from SSPxBUF clearing BF.
- 17. If SEN is set the slave sets CKP to release the SCLx.
- 18. Steps 13-17 repeat for each received byte.
- 19. Master sends Stop to end the transmission.

21.5.5 10-BIT ADDRESSING WITH ADDRESS OR DATA HOLD

Reception using 10-bit addressing with AHEN or DHEN set is the same as with 7-bit modes. The only difference is the need to update the SSPxADD register using the UA bit. All functionality, specifically when the CKP bit is cleared and SCLx line is held low are the same. Figure 21-21 can be used as a reference of a slave in 10-bit addressing with AHEN set.

Figure 21-22 shows a standard waveform for a slave transmitter in 10-bit Addressing mode.











21.7 BAUD RATE GENERATOR

The MSSP module has a Baud Rate Generator available for clock generation in both I²C and SPI Master modes. The Baud Rate Generator (BRG) reload value is placed in the SSPxADD register (Register 21-6). When a write occurs to SSPxBUF, the Baud Rate Generator will automatically begin counting down.

Once the given operation is complete, the internal clock will automatically stop counting and the clock pin will remain in its last state.

An internal signal "Reload" in Figure 21-40 triggers the value from SSPxADD to be loaded into the BRG counter. This occurs twice for each oscillation of the

module clock line. The logic dictating when the reload signal is asserted depends on the mode the MSSP is being operated in.

Table 21-4 demonstrates clock rates based on instruction cycles and the BRG value loaded into SSPxADD.

EQUATION 21-1:

$$FCLOCK = \frac{FOSC}{(SSPxADD+1)(4)}$$

FIGURE 21-40: BAUD RATE GENERATOR BLOCK DIAGRAM



Note: Values of 0x00, 0x01 and 0x02 are not valid for SSPxADD when used as a Baud Rate Generator for I²C. This is an implementation limitation.

TABLE 21-4: MSSP CLOCK RATE W/BRG

Fosc	Fcy	BRG Value	FCLOCK (Two Rollovers of BRG)
16 MHz	4 MHz	09h	400 kHz
16 MHz	4 MHz	0Ch	308 kHz
16 MHz	4 MHz	27h	100 kHz
4 MHz	1 MHz	09h	100 kHz

Note: Refer to the I/O port electrical and timing specifications in Table 29-9 and Figure 29-7 to ensure the system is designed to support the I/O timing requirements.

21.8 Register Definitions: MSSP Control

REGISTER 21-1: SSPxSTAT: SSP STATUS REGISTER

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-0/0	R-0/0	R-0/0	R-0/0
SMP	CKE	D/Ā	Р	S	R/W	UA	BF
bit 7	•	·			·	· ·	bit 0
Legend:							
R = Readable bit		W = Writable bit	t	U = Unimpleme	ented bit, read as	ʻ0'	
u = Bit is unchan	ged	x = Bit is unknow	wn	-n/n = Value at	POR and BOR/Va	alue at all other F	Resets
'1' = Bit is set		'0' = Bit is cleare	ed				
bit 7	SMP: SPI Data	Input Sample bit	t				
	SPI Master mod 1 = Input data s 0 = Input data s	<u>de:</u> ampled at end o ampled at middle	f data output tin e of data output	ne t time			
	SPI Slave mode SMP must be c In I ² C Master of	<u>e:</u> leared when SPI <u>r Slave mode:</u>	is used in Slav	e mode			
	1 = Slew rate o 0 = Slew rate o	control disabled					
bit 6	CKE: SPI Clock	< Edge Select bit	(SPI mode only	y)			
	1 = Transmit oc	curs on transition	n from active to	Idle clock state			
	In I ² C [™] mode o	only:					
	1 = Enable inpu 0 = Disable SM	it logic so that thi Bus specific inpu	resholds are co its	mpliant with SM	Bus specification		
bit 5	D/A: Data/Addm 1 = Indicates th 0 = Indicates th	ess bit (I ² C mode at the last byte re at the last byte re	e only) eceived or trans eceived or trans	smitted was data smitted was add	ress		
bit 4	P: Stop bit						
	 (I²C mode only. 1 = Indicates th 0 = Stop bit was 	This bit is cleare at a Stop bit has s not detected las	ed when the MS been detected st	SP module is di last (this bit is '0	sabled, SSPEN is ' on Reset)	cleared.)	
bit 3	S: Start bit						
	(I ² C mode only. 1 = Indicates th 0 = Start bit was	This bit is cleare at a Start bit has s not detected las	ed when the MS been detected st	SP module is di last (this bit is '0	sabled, SSPEN is o' on Reset)	cleared.)	
bit 2	R/W: Read/Writ	te bit information	(I ² C mode only	<i>י</i>)			
	This bit holds th to the next Start In I^2C Slave module 1 = Read 0 = Write	e R/W bit informa t bit, Stop bit, or r <u>ode:</u>	atio <u>n foll</u> owing tl not ACK bit.	ne last address n	natch. This bit is o	nly valid from the	address match
	$\frac{\ln l^2 C \text{ Master m}}{1 = \text{ Transmit is}}$ $0 = \text{ Transmit is}$ OR-ing thi	<u>node:</u> s in progress s not in progress is bit with SEN. F	RSEN. PEN. RC	EN or ACKEN v	vill indicate if the N	MSSP is in Idle m	ode.
bit 1	UA: Update Add 1 = Indicates th	dress bit (10-bit I at the user need	² C mode only) s to update the	address in the S	SPxADD register		
bit 0		es not need to be Status hit	e upualed				
bit o	Receive (SPI and 1 = Receive con 0 = Receive not	nd I ² C modes): mplete, SSPxBU t complete, SSP>	F is full kBUF is empty				
	$\frac{\text{Transmit (I}^2 \text{C m})}{1 = \text{Data transmit}}$ $0 = \text{Data transmit}$	node only): nit in progress (de nit complete (doe	oes not include es not include th	the \overline{ACK} and Stope ACK and Stope	op bits), SSPxBUI b bits), SSPxBUF i	F is full s empty	

TABLE 24-3:	SUMMARY OF REGISTERS ASSOCIATED WITH CLCx
-------------	---

Name	Bit7	Bit6	Bit5	Bit4	Blt3	Bit2	Bit1	Bit0	Register on Page
ANSELA	_		—	ANSA4	—	ANSA2	ANSA1	ANSA0	110
ANSELB	_	_	ANSB5	ANSB4	—	—	—	—	114
ANSELC	ANSC7	ANSC6	—	—	ANSC3	ANSC2	ANSC1	ANSC0	118
CLC1CON	LC1EN	LC10E	LC10UT	LC1INTP	LC1INTN	LC1MODE<2:0>			263
CLCDATA	_	_	_	_	_	MLC3OUT	MLC2OUT	MLC1OUT	271
CLC1GLS0	LC1G1D4T	LC1G1D4N	LC1G1D3T	LC1G1D3N	LC1G1D2T	LC1G1D2N	LC1G1D1T	LC1G1D1N	267
CLC1GLS1	LC1G2D4T	LC1G2D4N	LC1G2D3T	LC1G2D3N	LC1G2D2T	LC1G2D2N	LC1G2D1T	LC1G2D1N	268
CLC1GLS2	LC1G3D4T	LC1G3D4N	LC1G3D3T	LC1G3D3N	LC1G3D2T	LC1G3D2N	LC1G3D1T	LC1G3D1N	269
CLC1GLS3	LC1G4D4T	LC1G4D4N	LC1G4D3T	LC1G4D3N	LC1G4D2T	LC1G4D2N	LC1G4D1T	LC1G4D1N	270
CLC1POL	LC1POL	_	_	_	LC1G4POL	LC1G3POL	LC1G2POL	LC1G1POL	264
CLC1SEL0	_		LC1D2S<2:0>		—		LC1D1S<2:0>		265
CLC1SEL1	_		LC1D4S<2:0>		—		LC1D3S<2:0>		266
CLC2CON	LC2EN	LC2OE	LC2OUT	LC2INTP	LC2INTN	L	C2MODE<2:0	>	263
CLC2GLS0	LC2G1D4T	LC2G1D4N	LC2G1D3T	LC2G1D3N	LC2G1D2T	LC2G1D2N	LC2G1D1T	LC2G1D1N	267
CLC2GLS1	LC2G2D4T	LC2G2D4N	LC2G2D3T	LC2G2D3N	LC2G2D2T	LC2G2D2N	LC2G2D1T	LC2G2D1N	268
CLC2GLS2	LC2G3D4T	LC2G3D4N	LC2G3D3T	LC2G3D3N	LC2G3D2T	LC2G3D2N	LC2G3D1T	LC2G3D1N	269
CLC2GLS3	LC2G4D4T	LC2G4D4N	LC2G4D3T	LC2G4D3N	LC2G4D2T	LC2G4D2N	LC2G4D1T	LC2G4D1N	270
CLC2POL	LC2POL	_	—	—	LC2G4POL	LC2G3POL	LC2G2POL	LC2G1POL	264
CLC2SEL0	_		LC2D2S<2:0>		—		LC2D1S<2:0>		
CLC2SEL1	_		LC2D4S<2:0>		—		LC2D3S<2:0>		266
CLC3CON	LC3EN	LC3OE	LC3OUT	LC3INTP	LC3INTN	L	263		
CLC3GLS0	LC3G1D4T	LC3G1D4N	LC3G1D3T	LC3G1D3N	LC3G1D2T	LC3G1D2N	LC3G1D1T	LC3G1D1N	267
CLC3GLS1	LC3G2D4T	LC3G2D4N	LC3G2D3T	LC3G2D3N	LC3G2D2T	LC3G2D2N	LC3G2D1T	LC3G2D1N	268
CLC3GLS2	LC3G3D4T	LC3G3D4N	LC3G3D3T	LC3G3D3N	LC3G3D2T	LC3G3D2N	LC3G3D1T	LC3G3D1N	269
CLC3GLS3	LC3G4D4T	LC3G4D4N	LC3G4D3T	LC3G4D3N	LC3G4D2T	LC3G4D2N	LC3G4D1T	LC3G4D1N	270
CLC3POL	LC3POL	_	_	_	LC3G4POL	LC3G3POL	LC3G2POL	LC3G1POL	264
CLC3SEL0	_		LC3D2S<2:0>		—		LC3D1S<2:0>		265
CLC3SEL1	_		LC3D4S<2:0>		—		LC3D3S<2:0>		266
CLC4CON	LC4EN	LC4OE	LC4OUT	LC4INTP	LC4INTN	L	C4MODE<2:0	>	263
CLC4GLS0	LC4G1D4T	LC4G1D4N	LC4G1D3T	LC4G1D3N	LC4G1D2T	LC4G1D2N	LC4G1D1T	LC4G1D1N	267
CLC4GLS1	LC4G2D4T	LC4G2D4N	LC4G2D3T	LC4G2D3N	LC4G2D2T	LC4G2D2N	LC4G2D1T	LC4G2D1N	268
CLC4GLS2	LC4G3D4T	LC4G3D4N	LC4G3D3T	LC4G3D3N	LC4G3D2T	LC4G3D2N	LC4G3D1T	LC4G3D1N	269
CLC4GLS3	LC4G4D4T	LC4G4D4N	LC4G4D3T	LC4G4D3N	LC4G4D2T	LC4G4D2N	LC4G4D1T	LC4G4D1N	270
CLC4POL	LC4POL	_	_	_	LC4G4POL	LC4G3POL	LC4G2POL	LC4G1POL	264
CLC4SEL0	_		LC4D2S<2:0>		—		LC4D1S<2:0>		265
CLC4SEL1	_		LC4D4S<2:0>		_		LC4D3S<2:0>		266
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	75
PIE3	_		—	—	CLC4IE	CLC3IE	CLC2IE	CLC1IE	78
PIR3	-	_	—	—	CLC4IF	CLC3IF	CLC2IF	CLC1IF	81
TRISA	-	_	TRISA5	TRISA4	(1)	TRISA2	TRISA1	TRISA0	109
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	113
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	117

 Legend:
 — = unimplemented read as '0',. Shaded cells are not used for CLC module.

 Note
 1:
 Unimplemented, read as '1'.



NOTES:

29.3 DC Characteristics

TABLE 29-1: SUPPLY VOLTAGE

PIC16LF	1508/9		Standard Operating Conditions (unless otherwise stated)					
PIC16F1	508/9							
Param. No.	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions	
D001	Vdd	Supply Voltage						
			VDDMIN 1.8 2.5	_	VDDMAX 3.6 3.6	V V	Fosc ≤ 16 MHz Fosc ≤ 20 MHz	
D001			2.3 2.5	_	5.5 5.5	V V	Fosc ≤ 16 MHz Fosc ≤ 20 MHz	
D002*	Vdr	RAM Data Retention Voltage ⁽¹⁾						
			1.5		—	V	Device in Sleep mode	
D002*			1.7	_	—	V	Device in Sleep mode	
D002A*	VPOR	Power-on Reset Release Voltage	2)					
			—	1.6	—	V		
D002A*			_	1.6	—	V		
D002B*	VPORR*	Power-on Reset Rearm Voltage ⁽²⁾						
			—	0.8	_	V		
D002B*				1.5		V		
D003	VFVR	Fixed Voltage Reference Voltage						
		1x gain (1.024V nominal) 2x gain (2.048V nominal) 4x gain (4.096V nominal)	-4 -3	_	+4 +7	%	$\label{eq:VDD} \begin{array}{l} VDD \geq 2.5V, \ -40^{\circ}C \leq TA \leq +85^{\circ}C \\ VDD \geq 2.5V, \ -40^{\circ}C \leq TA \leq +85^{\circ}C \\ VDD \geq 4.75V, \ -40^{\circ}C \leq TA \leq +85^{\circ}C \\ \end{array}$	
D004*	SVDD	VDD Rise Rate ⁽²⁾	0.05	—	_	V/ms	Ensures that the Power-on Reset signal is released properly.	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: See Figure 29-3, POR and POR REARM with Slow Rising VDD.



3:

TvLow 2.7 µs typical.

PIC16LF1508/9		Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode										
PIC16F1508/9		Low-Power Sleep Mode, VREGPM = 1										
Param.	Device Of an effective		-	Max.	Max.		Conditions					
No.	Device Characteristics	wiin.	турт	+85°C	+125°C	Units	Vdd	Note				
D022	Base IPD		0.020	1.0	8.0	μA	1.8	WDT, BOR, FVR and SOSC				
		—	0.025	2.0	9.0	μA	3.0	disabled, all Peripherals inactive				
D022	Base IPD	_	0.25	3.0	10	μA	2.3	WDT, BOR, FVR and SOSC				
		—	0.30	4.0	12	μA	3.0	disabled, all Peripherals inactive,				
		—	0.40	6.0	15	μA	5.0	Low-Power Sleep mode				
D022A	Base IPD	_	9.8	16	18	μA	2.3	WDT, BOR, FVR and SOSC				
		_	10.3	18	20	μA	3.0	disabled, all Peripherals inactive,				
		_	11.5	21	26	μA	5.0	VREGPM = 0				
D023		—	0.26	2.0	9.0	μA	1.8	WDT Current				
		—	0.44	3.0	10	μA	3.0					
D023		_	0.43	6.0	15	μA	2.3	WDT Current				
		—	0.53	7.0	20	μA	3.0					
		—	0.64	8.0	22	μA	5.0					
D023A		_	15	28	30	μA	1.8	FVR Current				
		—	18	30	33	μA	3.0					
D023A		—	18	33	35	μA	2.3	FVR Current				
		_	19	35	37	μA	3.0					
			20	37	39	μA	5.0					
D024		—	6.0	17	20	μA	3.0	BOR Current				
D024			7.0	17	30	μA	3.0	BOR Current				
		—	8.0	20	40	μA	5.0					
D24A		—	0.1	4.0	10	μA	3.0	LPBOR Current				
D24A		_	0.35	5.0	14	μA	3.0	LPBOR Current				
		—	0.45	8.0	17	μA	5.0					

TABLE 29-3: POWER-DOWN CURRENTS (IPD)^(1,2)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral ∆ current can be determined by subtracting the base IPD current from this limit. Max. values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to Vss.

3: ADC clock source is FRC.

FIGURE 29-5: CLOCK TIMING



TABLE 29-7: CLOCK OSCILLATOR TIMING REQUIREMENTS

Param. No.	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions
OS01	Fosc	External CLKIN Frequency ⁽¹⁾	DC		0.5	MHz	External Clock (ECL)
			DC	—	4	MHz	External Clock (ECM)
			DC	—	20	MHz	External Clock (ECH)
		Oscillator Frequency ⁽¹⁾	_	32.768	_	kHz	LP Oscillator
			0.1	—	4	MHz	XT Oscillator
			1	—	4	MHz	HS Oscillator
			1	—	20	MHz	HS Oscillator, VDD > 2.7V
			DC	—	4	MHz	EXTRC, VDD > 2.0V
OS02	Tosc	External CLKIN Period ⁽¹⁾	27		×	μs	LP Oscillator
			250	—	∞	ns	XT Oscillator
			50	—	∞	ns	HS Oscillator
			50	—	∞	ns	External Clock (EC)
		Oscillator Period ⁽¹⁾	_	30.5	_	μs	LP Oscillator
			250	—	10,000	ns	XT Oscillator
			50	—	1,000	ns	HS Oscillator
			250	—	—	ns	EXTRC
OS03	TCY	Instruction Cycle Time ⁽¹⁾	200	Тсү	DC	ns	Tcy = 4/Fosc
OS04*	TosH,	External CLKIN High	2	_	_	μs	LP Oscillator
	TosL	External CLKIN Low	100	—	—	ns	XT Oscillator
			20	—	—	ns	HS Oscillator
OS05*	TosR,	External CLKIN Rise	0	—	—	ns	LP Oscillator
	TosF	External CLKIN Fall	0	—	—	ns	XT Oscillator
			0	—	—	ns	HS Oscillator

Standard Operating Conditions (unless otherwise stated)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to CLKIN pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

FIGURE 29-7: CLKOUT AND I/O TIMING



TABLE 29-9:	CLKOUT	AND I/O	TIMING	PARAMETERS

Standard Operating Conditions (unless otherwise stated)										
Param. No.	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions			
OS11	TosH2ckL	Fosc↑ to CLKOUT↓ ⁽¹⁾	_		70	ns	$3.3V \le V\text{DD} \le 5.0V$			
OS12	TosH2ckH	Fosc↑ to CLKOUT↑ ⁽¹⁾	—	1	72	ns	$3.3V \le V\text{DD} \le 5.0V$			
OS13	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	1	20	ns				
OS14	TioV2ckH	Port input valid before CLKOUT ⁽¹⁾	Tosc + 200 ns			ns				
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	$3.3V \le V\text{DD} \le 5.0V$			
OS16	TosH2iol	Fosc↑ (Q2 cycle) to Port input invalid (I/O in setup time)	50			ns	$3.3V \le V\text{DD} \le 5.0V$			
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	_	_	ns				
OS18*	TioR	Port output rise time	—	40	72	ns	VDD = 1.8V			
			—	15	32		$3.3V \le V\text{DD} \le 5.0V$			
OS19*	TioF	Port output fall time	—	28	55	ns	VDD = 1.8V			
			—	15	30		$3.3V \le V\text{DD} \le 5.0V$			
OS20*	Tinp	INT pin input high or low time	25	_	—	ns				
OS21*	Tioc	Interrupt-on-change new input level time	25	_	_	ns				
* These parameters are characterized but not tested										

These parameters are characterized but not tested.

Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. †

Note 1: Measurements are taken in EXTRC mode where CLKOUT output is 4 x Tosc.















